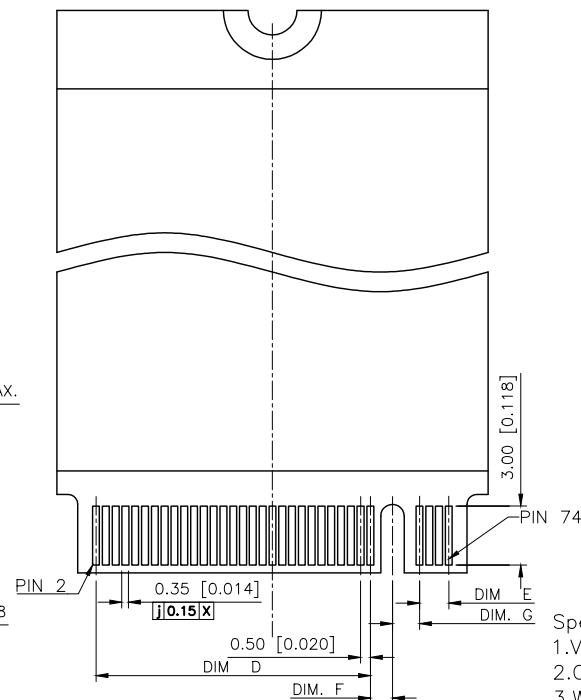
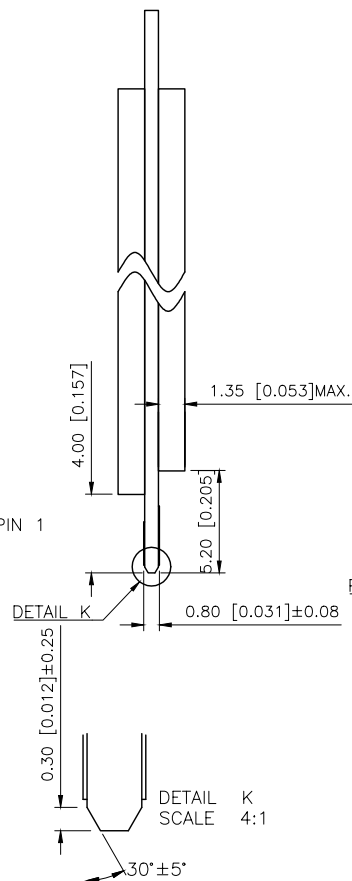
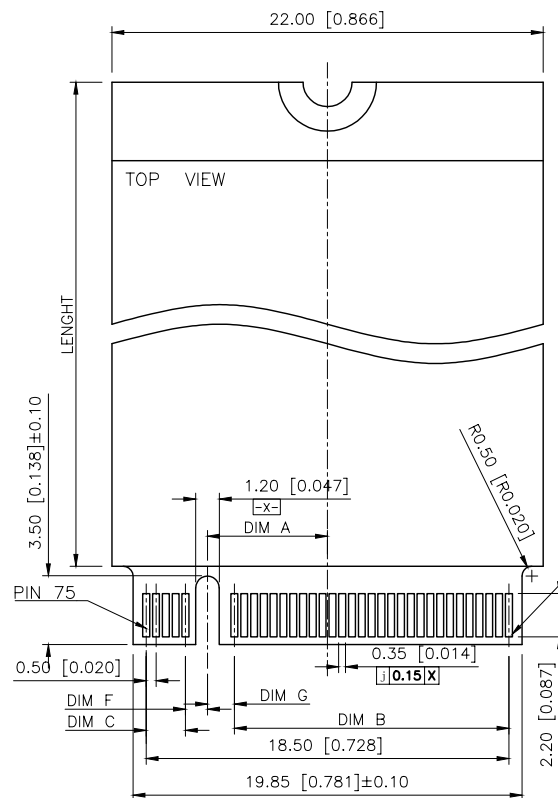


	REVISIONS				
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.1.14	阿树



PART NO.:

X1302 W V S-67 E A-LP V30
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨

- ①Series Number
- ②Terminal form: WAFER
- ③Welding Board Angle : V—Stright Angle 180°
- ④Welding Way:S—SMT
- ⑤No.of Pins: 67PIN
- ⑥HEIGHT: A:3.2mm;B:3.5mm;C:4.2mm;
D:5.5mm;E:6.7mm;F:8.5mm
- ⑦KEY ID: A,B,C,D,E,F,G,H,J,K,L,M
- ⑧Plastic material: LCP
- ⑨Contact Plating:V01 01"u";
V15 15"u";
V30 30"u"

Specifications(规格):

- 1.Voltage rating(额定电压):DC 36V
- 2.Current rating(额定电流):0.5A
- 3.Withstanding voltage(耐压值): $\geq 300V$ AC/minute
- 4.Insulation resistance(绝缘电阻): $\geq 500M\Omega$ Min
- 5.Contact resistance(接触电阻): $\leq 55m\Omega$ Max
- 6.Mating cycles (使用寿命) : 60 mate/unmate cycles for 15u" & 30u" Au plating; 25 mate/unmate cycles for gold flash plating
- 7.Mating Force (插拔力) : 2.55KgF Max
- 8.Temperature range(使用温度): $-40^{\circ}C \sim +80^{\circ}C$

1.375	1.125	1.50	14.00	2.00	14.00	6.125	M
1.375	1.125	2.50	13.00	3.00	13.00	5.125	L
1.375	1.125	3.50	12.00	4.00	12.00	4.125	K
1.375	1.125	4.50	11.00	5.00	11.00	3.125	J
1.375	1.125	5.50	10.00	6.00	10.00	2.125	H
1.375	1.125	6.50	9.00	7.00	9.00	1.125	G
DIM. G	DIM. F	DIM. E	DIM. D	DIM. C	DIM. B	DIM. A	KEY ID

1.125	1.375	9.50	6.00	9.50	6.50	-1.625	F
1.125	1.375	10.50	5.00	10.50	5.50	-2.625	E
1.125	1.375	11.50	4.00	11.50	4.50	-3.625	D
1.125	1.375	12.50	3.00	12.50	3.50	-4.625	C
1.125	1.375	13.50	2.00	13.50	2.50	-5.625	B
1.125	1.375	14.50	1.00	14.50	1.50	-6.625	A
DIM. G	DIM. F	DIM. E	DIM. D	DIM. C	DIM. B	DIM. A	KEY ID

NOTES 注释:

1. MATERIAL 材料:
 - 1.1 HOUSING外壳: THERMOPLASTIC, HIGH TEMP.,
UL94V-0;
COLOR: BLACK.
 - 1.2 CONTACTS触点: COPPER ALLOY.
 - 1.3 FITTING NAIL装配钉: COPPER ALLOY.
2. FINISH饰面:
 - 2.1 CONTACT触点:
[SEE TABLE] GOLD PLATING ON THE CONTACT AREA.
GOLD FLASH PLATING ON THE SOLDERING AREA.
1.27um~2.54um [50u"~100u"] MIN. NICKEL
UNDERPLATING OVERALL
 - 2.2 FITTING NAIL装配钉:
2.54um~5.08um [100u"~200u"] MIN. MATTE - TIN
PLATING ON THE SOLDERING AREA
1.27um~2.54um [50u"~100u"] MIN. NICKEL
UNDERPLATING OVERALL.
3. PACKING SPEC包装规范: K-91302-401

AuGLAR	$\pm 5^\circ$
X.	± 0.40
X.x	± 0.30
X.xx	± 0.20
X.xxx	± 0.15
UNSPECIFIED TOLERANCES	

XK13 星城 Connection

DESIGN

阿树

VIEW: 

MODEL TYPE:
2.50mm BTR Connector

CHECKED

UNIT: mm/i

PART NO.:

APPROVED

SIZE: A4

DWG NO.:

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	2/3	A1

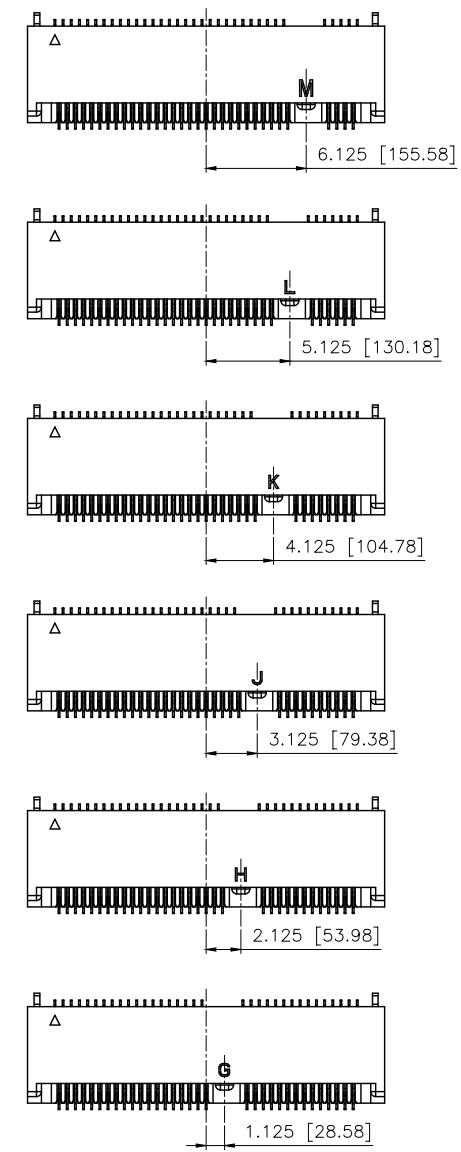
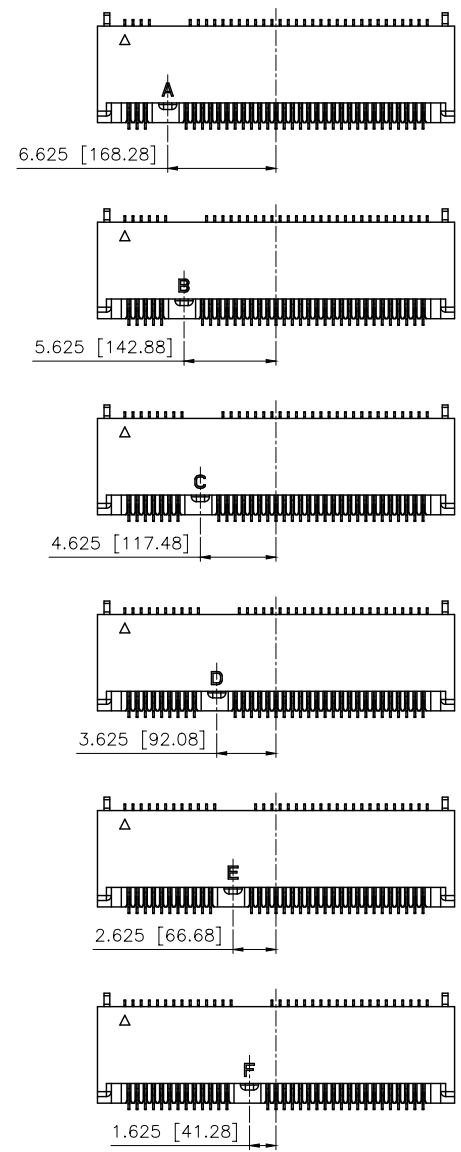
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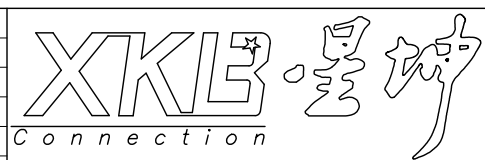
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4

REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.1.14	阿树



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树
CHECKED	
APPROVED	

VIEW:	
UNIT:	mm/in
SIZE:	A4

MODEL TYPE: 0.50mm BTB Connector		
PART NO.: X1302WVS-67EA-LPV30		
DWG NO.:		

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	3/3	A1

1

2

3

4